





### 1. Features:

The features of LCD are as follows:

- Display mode : STN /BLUE, NEGATIVE, TRANSMISSIVE
- Colour : Display dot: WHITE

Background: BLUE

- Display Format : 16 (characters) ×2 (line)
- \* IC : 7066 7065
- Interface Input Data : 8 Bits
- Driving Method : 1/16 Duty, 1/4 Bias
- Viewing Direction: 6 O'clock
- Backlight : LED (WHITE)

### 2. Mechanical Specifications:

Item	Specification	Unit
Module Size	122.00(W) X43.69(H) X13.4(T)	mm
Viewing Area	99.00(W) X 23.99(H)	mm
Effective Display Area	95.02(W) X 20.18(H)	mm
Number of Dots	16(characters) $\times$ 2(line)	-
Dot Size	1.08(W) X 0.94(H)	mm
Dot Pitch	1.16(W) X 1.02(H)	mm



### **3. Electrical Specifications:**

#### **1.** Absolute Maximum Ratings (Vss = 0V)

ltem	Symbol	Sta	Unit				
Rem	Oymbol	Min.	Тур.	Max.	Omt		
Supply Voltage For Logic	Vdd	-0.3	-	5.0	V		
Supply Voltage For LCD Drive	V0, Vоит	-0.3	-	14.5	V		
Operating Temp.	Тор	-20	-	+70	°C		
Storage Temp.	Ts⊤	-30	-	+80	°C		
Static Electricity	Be sure that you are ground when handing LCM						

#### 2. Electrical Characteristics:

Item		Symbol	Test Condition	Min.	Тур.	Max.	Unit
Supply Voltage	For Logic	Vdd – Vss	<b>Ta=25</b> ℃	4.8	5.0	5.2	V
Supply Voltage	For LCD	Vdd – Vo	<b>Ta=25</b> ℃	3.8	4.0	4.2	V
	"H" Lev <mark>e</mark> l	V IH	<b>Ta=25</b> ℃	0.8Vdd	-	Vdd	V
Input Voltage	"L" Level	VIL	1 <b>a-25</b> C	Vss	-	0.2Vdd	V
Output Voltage	"H" Level	V он	I <sub>OUT</sub> = -0.5mA	0.8VDD	-	Vdd	V
Output voltage	"L" Level	V ol	I <sub>OUT</sub> = 0.5mA	Vss	-	0.2Vdd	V
Current Consumption		I <sub>DD</sub>	$V_{IN} = V_{DD}$	-	-	1.0	mA

NOTE: 1) Duty ratio=1/65, Bias=1/9 2) Measured in Dots ON-state



#### 3. BACKLIGHT:

#### **3.1** Absolute Maximum Ratings:

Item	Symbol	Condition	Min.	Тур.	Max	Unit
Forward Current	IF	<b>Ta=25</b> ℃	-	-	20	mA
Reverse Voltage	VR	1a=25 C	-	-	5	V
Power Dissipation	PD	<b>Ta= 25</b> ℃	-	-	100	mW

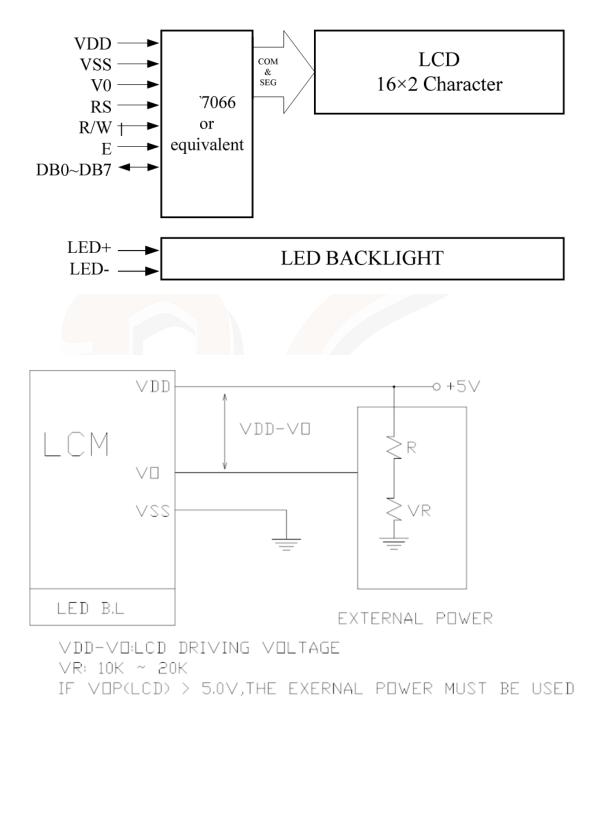
### **3.2** Opto-electronic Characteristics:

ltem	Symbol	Condition	Min.	Тур.	Max	Unit
Forward Voltage	VF	Ta= 25℃	4.8	5.0	5.2	V
Luminous	-	IF= 32mA	100	150	-	cd/m²

\* The brightness is measured without LCD panel



### 4. Schematic Design:





# **5. Interface Pin Function:**

Pin No.	Pin Out	Description
1	VSS	GND
2	VDD	Logic supply voltage (5.0V)
3	VO	Power supply for LCD
4	RS	Data/Instruction RS=high: Indicates that data of DB0~DB7 is display data. RS=low: Indicates that data of DB0~DB7 is instruction
5	R/W	Read/Write R/W=high: Data of DB0~DB7 can be read by CPU. R/W=low: Data of DB0~DB7 can be written into LCD driver IC
6	E	Enable When write(R/W=low): Data of DB0~DB7 is latched at the fall of E When read(R/W=high): Data is read while E is at high level.
7	DB0	
8	DB1	
9	DB2	
10	DB3	Data Bus line.
11	DB4	
12	DB5	
13	DB6	
14	DB7	
15	А	LED Backlight +./LED Backlight
16	K	LED Backlight/LED Backlight +.



### 6. Command List:

#### Instruction Table:

				Inst	ructi	on (	Code		Description			
Instruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Description	Time (270KHz)
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM. and set DDRAM address to "00H" from AC	1.52 ms
Return Home	0	0	0	0	0	0	0	0	1	x	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	1.52 ms
Entry Mode Set	0	0	0	0	0	0	0	1	١/D	s	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.	37 us
Display ON/OFF	0	0	0	0	0	0	1	D	с	в	D=1:entire display on C=1:cursor on B=1:cursor position on	37 us
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	x	x	Set cursor moving and display shift control bit, and the direction, without changing DDRAM data.	37 us
Function Set	0	0	0	0	1	DL	N	F	x	x	DL:interface data is 8/4 bits N:number of line is 2/1 F:font size is 5x11/5x8	37 us
Set CGRAM address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter	37 us
Set DDRAM address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter	37 us
Read Busy flag and address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0 us
Write data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM)	37 us
Read data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM)	37 us

#### Note:

Be sure the ST7066U is not in the busy state (BF = 0) before sending an instruction from the MPU to the ST7066U. If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself. Refer to Instruction Table for the list of each instruction execution time.



## 7. Timing Characteristics (Continued):

AC Characteristers $(VDD - 2.7) = -30 \approx 100$ C)									
Mode	Characteristeics	Symbol	Min	Тур	Max	Unit			
	Clock Pulse Width (Hight Low)	Tc	500	-	-				
Interface Mode	Clock Rise / Fall Time	Tr,Tf	-	-	20				
With	Clock Setup Time	Tsu1	500	-	-				
Extension Driver	Data Setup Time	Tsu2	300	-	-	ns			
(Refer to Fig-8)	Data Hold Time	Tdh	300	-	-				
	M Delay Time	TDM	-1000	-	1000				

#### AC Characteristeics (VDD = 2.7 V ~ 4.5 V,Ta= -30 ~ +85°C)

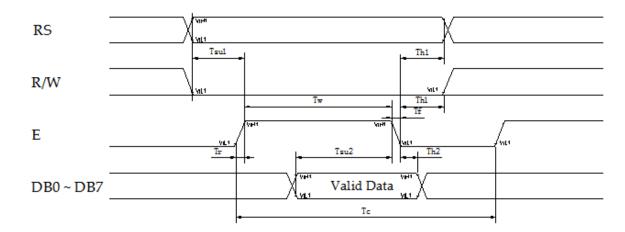


Figure 6. Write Mode Timing Diagram



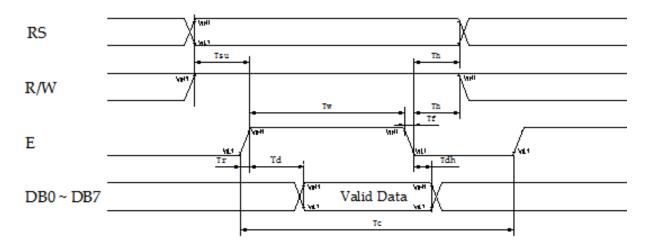


Figure 7. Read Mode Timing Diagram

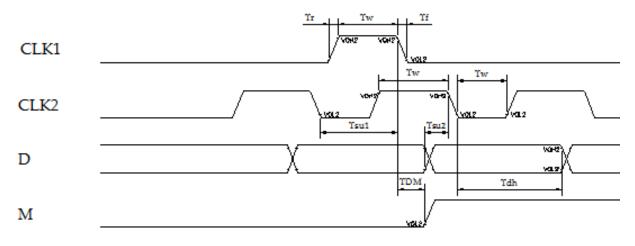


Figure 8. Interface Mode With Extension Driver Timing Diagram



# 8. Quality Specification (Continued):

#### 8-3. Sampling Plan and Acceptance

#### 1. Sampling Plan

MIL - STD - 105E ( **II** ) ordinary single inspection is used.

#### 2. Acceptance

Major defect:	AQL = 0.25%
Minor defect:	AQL = 0.65%

#### 8-4. Criteria

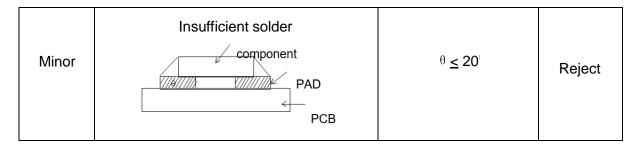
#### a) COB

Defect	Inspection Item	Inspection Standards			
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm <sup>2</sup>	Reject		
Major	Height of coating epoxy	coating epoxy Exceed the dimension of drawing			
Major	Void or hole of coating epoxy	Void or hole of coating epoxy Expose bonding wire or IC			
Major	PCB cutting defect	Exceed the dimension of drawing	Reject		

#### b) SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing , extra, wrong component or wrong orientation		Reject
Minor	$ \begin{array}{c}                                     $	X < 3/4Z Y > 1/3D	Reject Reject
Minor	soldering pad Component tilt	Y > 1/3D	Reject





#### c) Metal (Plastic) Frame

Defect	Inspection Item	Inspection Standards					
Major	Crack / breakage	Anywher	Reject				
		W	L	Acceptable of Scratch			
		w<0.03mm	Any	Ignore			
		0.03mm <u>&lt;</u> w<0.05mm	L <u>&lt;</u> 5.0mm	2			
Minor 🧹	Frame Scratch	0.05mm <w<0.1mm< td=""><td>L&lt;3.0mm</td><td>1</td></w<0.1mm<>	L<3.0mm	1			
		w>0.1mm	Any	0			
		Note: 1. Above criteria applicable to scratch lines with distance greater than 5mm. 2. Scratch on the back side of frame (not visible) can be ignored.					
				Acceptable of Dents / Pricks			
		⊕ <u>&lt;</u> 1.0mr	n	2			
		<b>1.0&lt;</b> Φ	2 <u>&lt;</u> 1.5mm	1			
	Frame Dent, Prick	1.5mm>0	Þ	0			
Minor	$\Phi = \frac{L + W}{2}$	Note: 1. Above criteria applicable to any two dents / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (not visible) can be ignored					
Minor	Frame Deformation	Exceed the dimension of drawing					
Minor	Metal Frame Oxidation		Any rust				



#### d) Flexible Film Connector (FFC)

Defect	Insp	ection Item	Inspection Standards			
Minor	Tilted soldering		Within the angle <u>+</u> 3°	Acceptable		
Minor	Uneven solder joint /bump			Reject		
		$\Phi = L + W$	Expose the conductive line	Reject		
Minor	Minor Hole $\Phi = 2$ $\Phi > 1.0$ mm			Reject		
	Position shift					
	$\gamma \xrightarrow{\psi} \overline{\psi}$		Y > 1/3D	Reject		
Minor						
		€	X > 1/2Z	Reject		

#### e) Screw

Defect Inspection Item		Inspection Standards			
Major	Screw missing/loosen		Reject		
Minor	Screw oxidation	Any rust	Reject		
Minor	Screw deformation	Difficult to accept screw driver	Reject		

#### f) Heat seal 、TCP 、FPC

Defect	Inspection Item	Inspection Standards		
Major	Scratch expose conductive layer		Reject	
Minor	HS Hole $\Phi = \frac{L + W}{2}$	⊕ > 0.2mm	Reject	
Major	Adhesion strength	Less than the specification	Reject	
Minor	Position shift	Y > 1/3D	Reject	
WIITO		X > 1/2Z	Reject	
Major	Conductive line break		Reject	



#### g) LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards				
		Acceptable number of units				
		⊕ <u>&lt;</u> 0.10mm	lgnore			
		0.10<⊕ <u>&lt;</u> 0.15mm	2			
Minor	LED dirty, prick	0.15<⊅ <u>&lt;</u> 0.2mm	1			
		Ф <b>&gt;0.2mm</b>	0			
		The distance between any two spots should be $\geq$ 10mm Any spot/dot/void outside of viewing area is acceptable				
Minor	Protective film tilt	t Not fully cover LCD				
Major	COG coating	Not fully cover ITO circuit	Reject			

#### h) Electric Inspection

Defect	Inspection Item	Inspection Standards	
Maj <mark>or</mark>	Short		Reject
Major	Open		Reject



Defect		Inspect Item	Inspection Standards							
		* Glass Scratch	W		W<0.03 0.03 <w<0.05< td=""><td></td><td>W&gt;0.05</td></w<0.05<>			W>0.05		
			L ACC.		L<5	5	L	_<3		Any
Minor	Linear Defect	* Polarizer Scratch	NO.				1		Reject	
		<ul> <li>Fiber and Linear material</li> </ul>	Note	L is the length and W is the width of the def				ect		
		* Foreign material	Φ	Φ<	Φ <u>&lt;</u> 0.1 0.1<Φ <u>&lt;</u> 0.15 0.15<			0.15<⊕ <u>&lt;</u>	<u>&lt;</u> 0.2	Ф <b>&gt;0.2</b>
	Black Spot and	between glass and polarizer or glass	ACC. NO.	3EA	/1PC	2		1		0
Minor	Polarizer Pricked	and glass * Polarizer hole or protuberance by external force	Note		$\Phi$ is the average diameter of the defect.Distance betwe two defects > 10mm.				stance between	
		* Unobvious	Φ	Ф <u>&lt;</u>	0.1	0.1<⊅ <u>&lt;</u>	0.15	0.15<⊅ <u>&lt;</u>	<u>&lt;</u> 0.2	Ф <b>&gt;0.2</b>
	White Spot and	transparent foreign material between	ACC. NO.	3EA/	1PC	2		1		0
Minor	White Spot and Bubble in polarizer	glass and glass or glass and polarizer * Air protuberance between polarizer and glass	Note	$\Phi$ is the average diameter of the defect.Distance betwee two defects > 10mm.			stance between			
			Φ	Ф <u>&lt;</u> (	0.10	) 0.10<⊕ <u>&lt;</u> 0.20			Ф <b>&gt;0.2</b>	
	Segment		ACC. NO.	3EA/1PC 2			0			
Minor				W is more than 1/2 segment width Rej			Reject			
MINO	Defect		Note	Distar	$\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm					
			Φ	Φ	<u>&lt;</u> 0.10		0.10<⊕ <u>&lt;</u> 0.20			<b>Φ&gt;0.2</b>
	Protuberant Segment		w	C	Glue W <u>&lt;</u> 1/2 Seg , W <u>&lt;</u> 0.2		2	Ignore		
Minor		$\Phi = (L + W)/2$	ACC. NO.	3EA/1PC 2			0			
		$\Psi = (L + W) / 2$		1. Segment						
Minor		X X	В		В <u>&lt;</u> 0	4mm 0.4 <e< td=""><td colspan="2">4<b<u>&lt;1.0mm E</b<u></td><td>B&gt;1.0mm</td></e<>		4 <b<u>&lt;1.0mm E</b<u>		B>1.0mm
			B-A		B-A<	:1/2B B-A		B-A<0.2 B-A<0.2		B-A<0.25
	Assembly Mis-	-B A	Judg			Acceptable Acceptable		Acceptable		
	alignment	0.35mm				2	. Dot l	Matrix		
				Deformation>0.35mm				Reject		

#### i) Inspection Specification of LCD



Minor	Stain on LCD Panel Surface		Accept when stains can be wiped lightly with a soft cloth or a similar one. Otherwise, judged according to the aboveitems: "Black spot" and "White Spot"
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### 9. Reliability:

NO.	ltem	Condition	Criterion	
1	High Temperature Operating	<b>70℃, 96Hrs</b>		
2	Low Temperature Operating	-20℃, 96Hrs		
3	High Humidity	40℃, 90%RH, 96Hrs		
4	High Temperature Storage	80℃, 96Hrs	No defect in cosmetic	
5	Low Temperature Storage	-30℃, 96Hrs	and operational function allowable.	
6	Vibration	Vibration Vibration Random wave 10 ~ 100Hz Acceleration: 2g 2 Hrs per direction(X,Y,Z)		
7	Thermal Shock	-10℃ to 25℃ to 60℃ (60Min) (5Min) (60Min) 16Cycles		
8	ESD Testing	Contract Discharge Voltage: +1 ~ $5kV$ and $-1 ~ -5kV$ Air Discharge Voltage: +1 ~ $8kV$ and $-1 ~ -8kV$	There will be discharged ten times at every discharging voltage cycle. The voltage gap is 1kV.	

*Note:* 1) Above conditions are suitable for xinnuoya standard products.

2) For restrict products, the test conditions listed as above must be revised.



### **10. Handling Precaution:**

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizerswhich easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling

the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommendedbelow) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichlorotrifloroethane

Do not wipe the display surface with dry or hard materials that will damage thepolarizer surface.

Do not use the following solvent:

- Water
- Ketone
- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before poweris turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

(4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shockand falls from a height.

- To prevent modules from degradation. Do not operate or store them exposeddirectly to sunshine or high temperature/humidity.

(5) Caution for operation

- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.



### Handling Precaution (Continued):

- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show darkcolor in them. However those phenomena do not mean malfunction or out of order with LCD's.Which will come back in the specified operating temperature range.

- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.

- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 60°C, 90% RH or less is required.

(6) Storage

In the case of storing for a long period of time (for instance, for years) for thepurpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it,And with no desiccant.

- Placing in a dark place where neither exposure to direct sunlight nor light is.

Keeping temperature in the specified storage temperature range.

- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)

(7) Safety

- It is recommendable to crash damaged or unnecessary LCD into pieces and washoff liquid crystal by using solvents such as acetone and ethanol.

Which should be burned up later.

When any liquid crystal leaked out of a damaged glass cell comes in contact withyour hands, please wash it off well with soap and water.



### **11. Outline Dimensions:**

